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<ul> <li>4.5-V to 5.5-V V<sub>CC</sub> Operation</li> <li>Wide Operating Temperature Range of -55°C to 125°C</li> </ul>	CD54HCT258 F PACKAGE CD74HCT258 E PACKAGE (TOP VIEW)
<ul> <li>Balanced Propagation Delays and</li></ul>	Ā/B [] 1 16] V <sub>CC</sub>
Transition Times	1A [] 2 15] G
<ul> <li>Standard Outputs Drive Up To 10 LS-TTL</li></ul>	1B [] 3 14 [] 4A
Loads	1Y [] 4 13 [] 4B
<ul> <li>Significant Power Reduction Compared to</li></ul>	2A [ 5 12 ] 4Y
LS-TTL Logic ICs	2B [ 6 11 ] 3A
Inputs Are TTL-Voltage Compatible	2Y [ 7 10 ] 3B GND [ 8 9 ] 3Y

#### description/ordering information

These devices are designed to multiplex signals from 4-bit data sources to 4-output data lines in bus-organized systems. The 3-state outputs do not load the data lines when the output-enable ( $\overline{G}$ ) input is at a high logic level.

To ensure the high-impedance state during power up or power down,  $\overline{G}$  should be tied to V<sub>CC</sub> through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

#### **ORDERING INFORMATION**

TA	PAC	KAGE <sup>†</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING		
–55°C to 125°C	PDIP – E	Tube	CD74HCT258E	CD74HCT258E		
-55 C 10 125 C	CDIP – F	Tube	CD54HCT258F3A	CD54HCT258F3A		

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

	INPU	OUTPUT									
G	Ā/B	Α	В	Y							
Н	Х	Х	Х	Z							
L	L	L	х	н							
L	L	н	х	L							
L	н	Х	L	Н							
L	Н	Х	Н	L							

#### FUNCTION TABLE



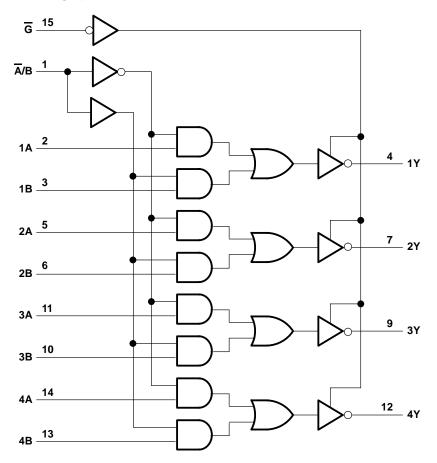
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#### logic diagram (positive logic)



#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)	±20 mA
Output clamp current, $I_{OK}$ (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> ) (see Note 1)	±20 mA
Continuous output drain current per output, $I_O(V_O = 0 \text{ to } V_{CC})$	±35 mA
Continuous output source or sink current per output, $I_O (V_O = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through V <sub>CC</sub> or GND	±50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): E package	69°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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### recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	V
VIH	High-level input voltage	2		V
VIL	Low-level input voltage		0.8	V
VI	Input voltage		VCC	V
Vo	Output voltage		VCC	V
$\Delta t / \Delta v$	Input transition rise or fall rate		500	ns
ТА	Operating free-air temperature	-55	125	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST	Vcc	T <sub>A</sub> = 2	25°C	T <sub>A</sub> = −55°C TO 125°C		T <sub>A</sub> = −40°C TO 85°C		UNIT		
				MIN	MAX	MIN	MAX	MIN	MAX		
Vou	$\lambda = \lambda = 0$	I <sub>OH</sub> = -20 μA	4.5 V	4.4		4.4		4.4		V	
VОН	V <sub>OH</sub> V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = –6 mA	4.5 V	3.98		3.7		3.84		v	
Vei	VI = VIH or VIL	I <sub>OL</sub> = 20 μA	4.5 V		0.1		0.1		0.1	V	
VOL		$I_{OL} = 6 \text{ mA}$	4.5 V		0.26		0.4		0.33		
Ц	$V_I = V_{CC} \text{ or } 0$		5.5 V		±0.1		±1		±1	μA	
loz	VO = ACC  or  0		5.5 V		±0.5		±10		±5	μΑ	
Icc	$V_I = V_{CC} \text{ or } 0,$	IO = 0	5.5 V		8		160		80	μA	
∆lCC <sup>†</sup>	One input at V <sub>CC</sub> – 2	4.5 V to 5.5 V	100	360		490		450	μΑ		
Ci				10		10		10	pF		
Co					20		20		20	pF	

<sup>†</sup>Additional quiescent supply current per input pin, TTL inputs high, 1 unit load. For dual-supply systems, theoretical worst-case ( $V_I = 2.4 \text{ V}, V_{CC} = 5.5 \text{ V}$ ) specification is 1.8 mA.

#### HCT INPUT LOADING TABLE

INPUT	UNIT LOAD					
G	1.5					
A or B	0.5					
Ā/B	1.5					
Unit Load	is Alcc limit					

specified in electrical characteristics table (e.g.,  $360 \ \mu A$  max at  $25^{\circ}$ C).



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#### switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	Vcc	т,	ק = 25°C	;	T <sub>A</sub> = - TO 12		T <sub>A</sub> = - TO 8		UNIT
		(001-01)	CAPACITANCE		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
	A or B	Δουγγ	CL = 50 pF	4.5 V			27		41		34	
<b>.</b>	AUD	Any Y	CL = 15 pF	5 V		11						ns
<sup>t</sup> pd Ā/B	Any Y	C <sub>L</sub> = 50 pF	4.5 V			34		51		43	115	
	A/B	Ally I	CL = 15 pF	5 V		14						
•	G	A	CL = 50 pF	4.5 V			28		42		35	ns
ten	G	Any Y	CL = 15 pF	5 V		11						115
<b>.</b>	G	Anv	CL = 50 pF	4.5 V			30		45		38	
<sup>t</sup> dis		Any Y	CL = 15 pF	5 V		12						ns
tt		Any Y	C <sub>L</sub> = 50 pF				12		18		15	ns

# operating characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C

	PARAMETER			
Cpd	Power dissipation capacitance per multiplexer <sup>†</sup>	49	pF	

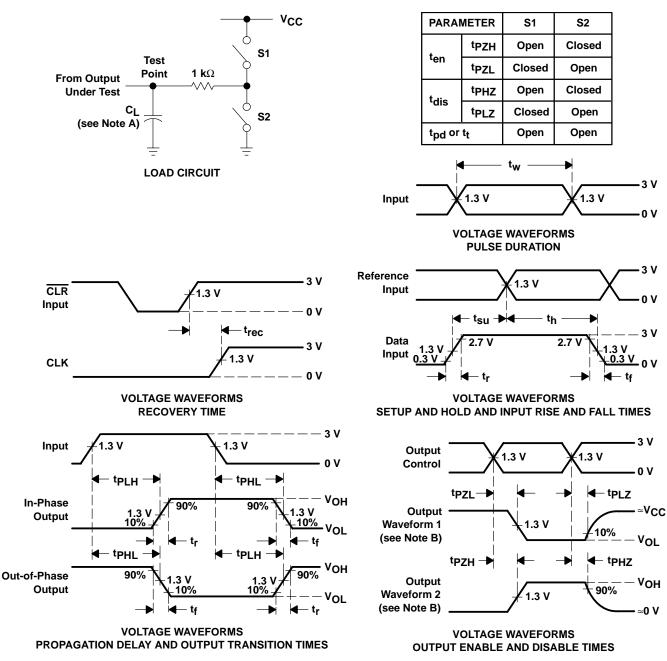
<sup>†</sup>  $C_{pd}$  is used to determine the dynamic power consumption per multiplexer.  $P_D = V_{CC}^2 fi (C_{pd} + C_L)$ where:  $P_D = dynamic power dissipation$ 

fi = input frequency

 $C_L$  = output load capacitance  $V_{CC}$  = supply voltage

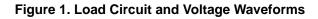


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PARAMETER MEASUREMENT INFORMATION

- NOTES: A. CL includes probe and test-fixture capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
     Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
     C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following
  - characteristics: PRR  $\leq$  1 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub> = 6 ns. t<sub>f</sub> = 6 ns.
  - D. For clock inputs,  $f_{max}$  is measured with the input duty cycle at 50%.
  - E. The outputs are measured one at a time with one input transition per measurement.
  - F.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - G.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - H. tpLH and tpHL are the same as  $t_{pd}$ .







### PACKAGING INFORMATION

Orderable Device	Status	Package Type	•	Pins	Package	Eco Plan	Lead finish/	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	Ball material	(3)		(4/5)	
							(6)				
5962-8970801EA	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8970801EA CD54HCT258F3A	Samples
CD54HCT258F3A	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8970801EA CD54HCT258F3A	Samples
CD74HCT258E	ACTIVE	PDIP	Ν	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT258E	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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# PACKAGE OPTION ADDENDUM

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#### OTHER QUALIFIED VERSIONS OF CD54HCT258, CD74HCT258 :

- Catalog : CD74HCT258
- Military : CD54HCT258

NOTE: Qualified Version Definitions:

#### Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications



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# TUBE



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
CD74HCT258E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT258E	N	PDIP	16	25	506	13.97	11230	4.32

J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



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